



Material Content Data Sheet



Sales Product Name				BAW 156 E6327		Issued		29. August 2013	
MA#				MA000494364					
Package				PG-SOT23-3-11		Weight*		8.80 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.006	0.07		680		
	non noble metal	arsenic	7440-38-2	0.000	0.00		7		
	inorganic material	silicon	7440-21-3	0.051	0.58	0.65	5810	6497	
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		925		
	inorganic material	silicon	7440-21-3	0.001	0.01		62		
	non noble metal	titanium	7440-32-6	0.003	0.03		309		
	non noble metal	copper	7440-50-8	2.704	30.72	30.85	307169	308465	
wire	noble metal	gold	7440-57-5	0.011	0.12	0.12	1193	1193	
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6557		
	plastics	brominated resin	-	0.087	0.98		9836		
	inorganic material	antimonytrioxide	1309-64-4	0.115	1.31		13114		
	plastics	epoxy resin	-	1.241	14.10		140977		
	inorganic material	silicondioxide	60676-86-0	4.272	48.52	65.57	485224	655708	
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16997	16997	
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11140	11140	
*deviation	< 10%		Sum in total:			100,00		1000000	

Important Remarks:

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